- Subclass	SSIFICATIO	2205
Class	SSUE CLASSIFICATIO	

U.S. UTILITY Patent Application
O.I.P.E. PATENT DATE

AP	PLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER	
	09/830434	DF	451	41	3723	Shaker	_
CINTAIN	Makoto Ko Hiroyuki	obayashi Takamats	ur e				.2
	Method ar	ed device	for poli	shing sem	iconductor	wafer	
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		ISSUING	CLASSIFICATION
ORIGINAL	(1)		CROSS REFERENCE(S)
CLASS	SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)
INTERNATIONAL	0.100		
INTERNATIONAL CL	ASSIFICATION		
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TERMINAL DISC! AIMER	DRAWINGS			CLAIMS ALLOWED	
DIOGRAMMEN	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
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The term of this patent subsequent to (date)				NOTICE OF AL	LOWANCE MAILED
has been disclaimed.	(Assistant E	xaminer)	(Date)		
The term of this patent shall not extend beyond the expiration date		. !			
of U.S Patent, No.				ISS	UE FEE
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The terminalmonths ofhis patent have been disclaimed.	* *			ISSUE BAT	CH NUMBER
	(Legal Instrument	s Examiner)	(Date)		
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